2SA1981

Rev.E Mar.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

WR0<5 ṂṂ Ḅ SQS ÆṀ ч s ‖ ㄱ Silicon PNP transistor in a TO-92 Plastic Package.

/ Features

ㅈ ⓦ ᶻ ı ль 5VF8677 Йꞌ

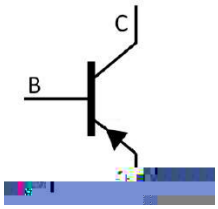
High h_{FE}, complementary pair with 2SC5344.

/ Applications

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Audio power amplifier application.

/ Equivalent Circuit



/ Pinning



PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

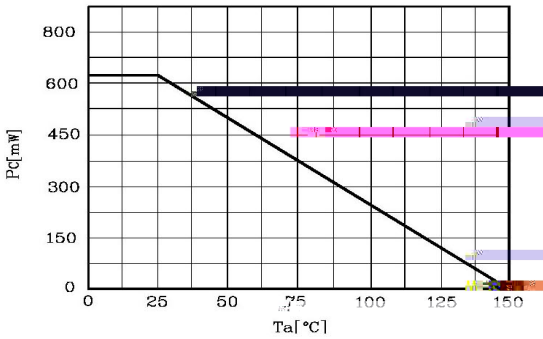
/ hFE Classifications & Marking

h_{FE} Classifications Symbol	O	Y
h_{FE} Range	100~200	160~320

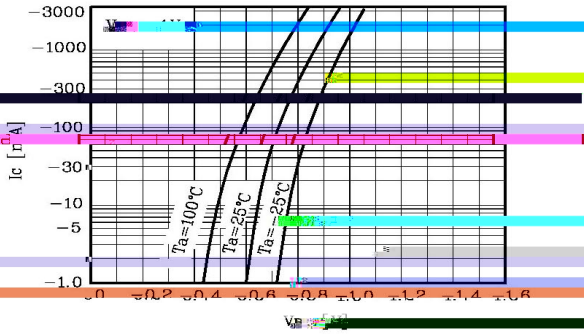
v ̈Ω	ϒ N	̈Ω Θ
Parameter	Symbol	

/ Electrical Characteristic Curve

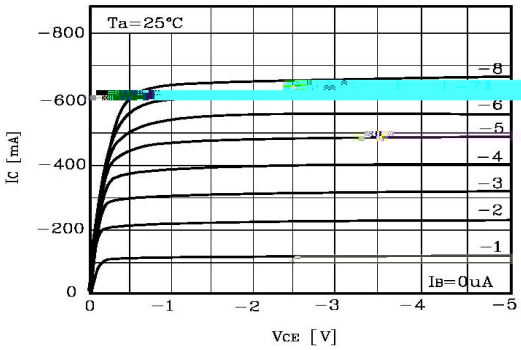
Pc-Ta



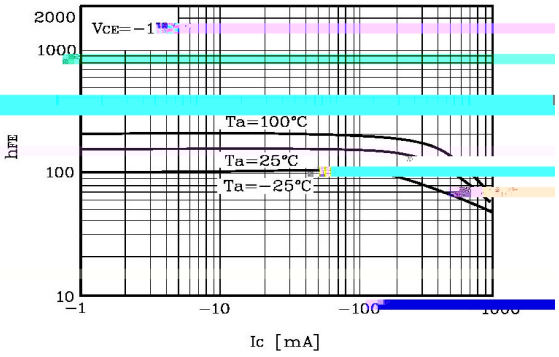
IC -V_{BE}



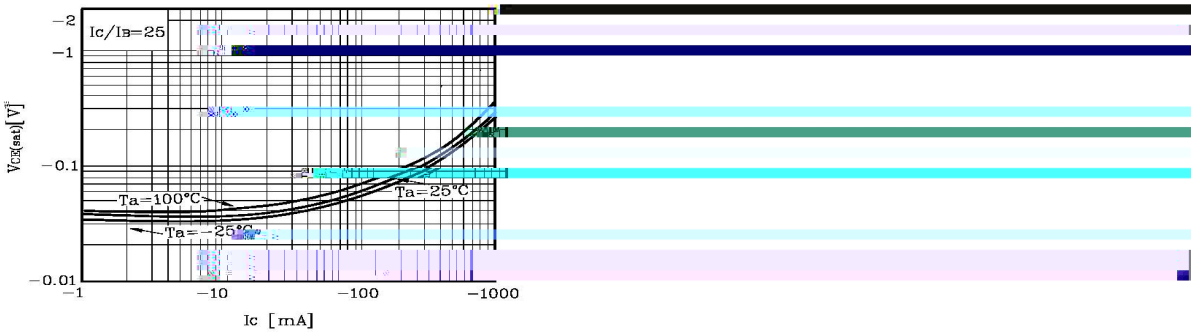
I_C - V_{CE}



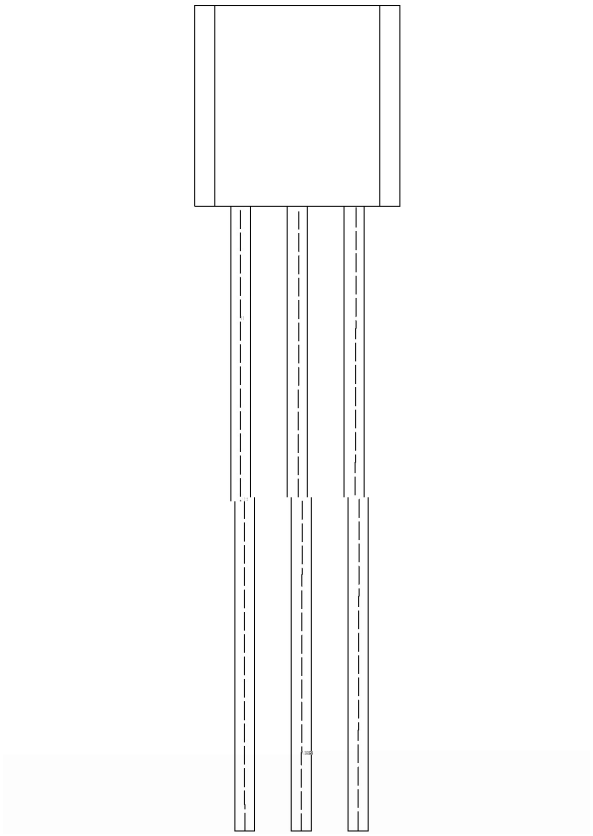
h_{FE} - I_C



$V_{CE(SAT)}$ - I_C



/ Marking Instructions



ب ˝ χ

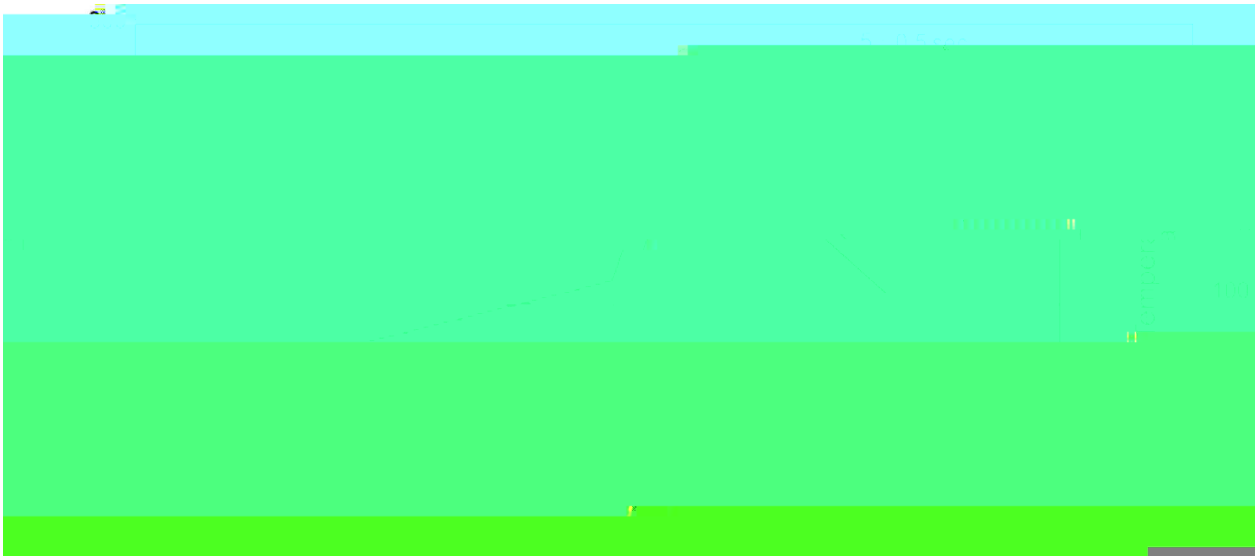
EU= ѭ ϛ И Ґђ

D4<;4 χ ѭ ʒ N Ґђ

\= ѭ h_{FE} ‘ 6 Ґђ

---- χ ѭ Ɔ N

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı `H ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 255 ° 5 ł ı `H ڑ `Y ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ﻉ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 270 ° 5 ł `H ڑ χ 10 ° 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

ˈQ ţ ﾘ Ł / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

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Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92	3,000	1	120	10	30,000	328×230×42	小箱 480×346×235， 大箱 547×407×268